

RoHS
Compliant



Description

High temperature masking tape and dots are ideal for masking gold fingers of printed circuit boards during wave solder or solder dip process, as well as for solder wave masking and electrical insulation.

This high temperature tape is a polyimide, pressure sensitive, adhesive tape with silicon resin, which shows excellent dielectric insulation properties, high heat resistance and excellent solvent resistance. These properties result in a tape with remarkable dimensional stability and excellent electrical and physical properties over a wide range of temperatures.

This product is neither corrosive nor ozone depleting and is both flame and chemical resistant.

	DIN Value:	ASTM Value:
Structure	Silicone Adhesive / Polyimide Film	
Base Film Thickness	0.025mm	1.0MIL
Total Thickness	0.07mm	2.8.MIL
Peel Strength	2.7N/CM	25oz/In
Tensile Strength	40N/CM	22lbs/In
Elongation	50%	50%
Heat Resistance (Short Term)	290°C	554°F
Heat Resistance	230°C	446°F
Appearance	Amber	Amber

Test Conditions

The following results were taken under the following environmental test conditions: Temperature: 22°C / Humidity: 46%

Item:	Test Standard:	Result:
Film Composition	N/A	PET-AL/NY/CPE
Metal Layer Resistance	ASTMD-257	<0.1Ω
Inner and Outer Resistance	ASTMD-257	10 ⁸ Ω - 10 ¹¹ Ω
Static Shielding - Capacitance Probe	EIA541 (Voltage Difference)	<10V
Moisture Vapour Transmission (at 90% RH, 23°C)	ASTMF1249-2005	0.02 gm/100sq.in/24hrs
Tensile Strength	ASTM D882	MD/TD >24lbs/in
Puncture Resistance	ASTM F1306-90(2002)	Inner to Outer: 54.7N Outer to Inner: 51.3N
Tear Strength	ASTM D1004	MD >3lbs/in TD >3.8lbs/in

Item:	Test Standard:	Result:
Heat Seal Temperature	-	250-375 F
Heat Seal Time	-	0.5-3.5 sec
Heat Seal Pressure	-	30-70 PSI
Seal Strength	GB/96-04-10	>3kg/cm
Contact Corrosivity	FTMS 101C Method 3005	No visible spots detected
Static Decay Time	IEC61340-5-1 (±1000 - ±100V)	≤2S

Test Conclusion:

The anti-static moisture barrier bag is tested accordant with the relevant test standard and requirements.

Test Item:	Test Method:	Measured Equipment(s):	MDL:
Lead (Pb)	IEC 62321:2008 Ed.1 Sec.8	ICP-OES	2mg/kg
Cadmium (Cd)	IEC 62321:2008 Ed.1 Sec.8	ICP-OES	2mg/kg
Mercury (Hg)	IEC 62321:2008 Ed.1 Sec.7	ICP-OES	2mg/kg
Hexavalent Chromium (Cr(VI))	IEC 62321:2008 Ed.1 Annex C	UV-Vis	2mg/kg
Polybrominated Biphenyls (PBBs)	IEC 62321:2008 Ed.1 Annex A	GC-MS	5mg/kg
Polybrominated Diphenyl Ethers (PBDEs)	IEC 62321:2008 Ed.1 Annex A	GC-MS	5mg/kg

EMI Shielding: Meets required range of EN 61340-5-1 tested per IEC 61340-2-3 and ANSI/ESD STM11.31

Part Number Table

Description	Part Number
High Temperature Masking Tape, Size 9mm, 152.4mm×711.2mm, PK100	051-0008

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